

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): WonSun Shin et al.

Assignee: Amkor Technology, Inc.

Title: STACKABLE SEMICONDUCTOR PACKAGE HAVING
SEMICONDUCTOR CHIP WITHIN CENTRAL THROUGH HOLE OF
SUBSTRATE

Serial No.: 10/803,333 Filed: March 17, 2004

Examiner: Luu, Chuong A. Group Art 2818
Unit:

Docket No.: GK0012-1C

Monterey, CA
June 3, 2005

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office Action dated February 4, 2005,
please amend the above-identified application as follows:

1. Amendments to the Specification begin on page 2
of this paper;
2. Amendments to the Claims are reflected in the
listing of Claims which begins on page 3 of this paper;
and
3. Remarks begin on page 8 of this paper.